

The diagram is a circular infographic. The outer ring is divided into six segments, each representing a different application area: Wireless, AI Clusters, Medical, Aerospace, Consumer, and Automotive. The inner ring is divided into four segments representing key performance indicators: Accuracy, Speed, Flexibility, and Reliability. These four segments are arranged around a central white circle containing the text 'MAXIMIZE ROI'. Arrows point from each of the four inner segments towards the center, indicating that these factors contribute to maximizing ROI.

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Patented turret for "on-the-fly" tool change

MRSI Systems has been serving optoelectronic and microelectronic customers for the past 40+ years and understands their requirement to scale efficiently in today's fast-paced marketplace.

Applications are found across a wide range of market segments, such as AI Clusters, Medical, Aerospace, Wireless, Automotive, Sensors, and more.

MRSI's die bonding solutions help our customers to enable just-in-time supply and fast-paced innovations of critical components for high-growth market segments. The ultra-flexible MRSI-705 and MRSI-M3 can be used for R&D prototyping to low/medium volume.

These die bonding solutions are built with the same hardware and software platforms configured to minimize process deviations, reduce NPI cost, and increase ROI for customers with MRSI's long proven product reliability and global customer support.

MRSI-M3, Highly Configurable



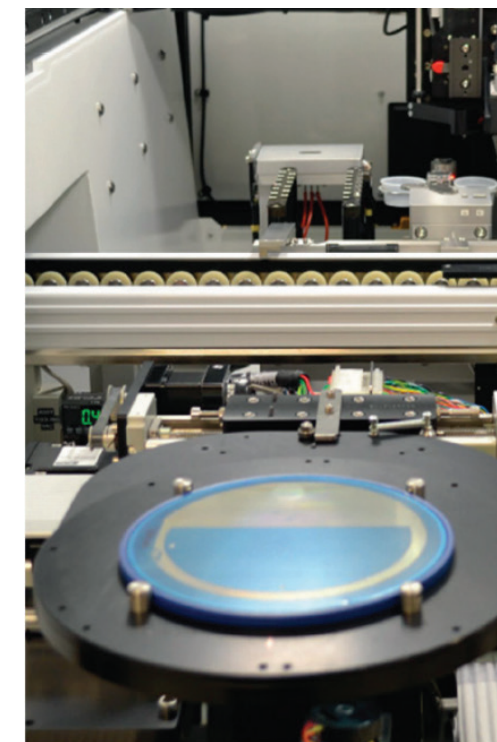
Assembly Technologies

- Eutectic Bonding
- Epoxy Die Attach
- In-situ UV Bonding
- Flip Chip Assembly
- Thermal Compression Bonding



All-In-One Platform

- Large Configurable Work Area
- Force Control for Advanced Assembly
- Advanced Machine Vision
- Programmable Multi-Color Lighting
- Quality Software, Computer and Motion Control
- Turnkey Integrated Production Lines



Configuration for Higher Speed and Volume



The MRSI-M3 offers an optional patented turret for “on-the-fly” tool change to significantly increase the production volume from our machine without sacrificing flexibility. The patented turret has the capacity for 12 tools with zero tool change time.

This leads to increased machine efficiency, higher output and lower manufacturing costs. Applications include processes requiring a large number of parts-specific tools, using eutectic bonding, and the need to assemble complex products with a multitude of component types.



Applications

- 3D Packaging
- Wafer Scale Packaging
- LED Assembly
- Microwave Modules
- Photonics Packaging
- RF Power Amplifiers
- Infrared Sensors
- Pressure Sensors
- MEMS Devices
- Semiconductor Packaging
- Hybrid Circuits
- Multichip Modules
- Pacemakers
- Hearing Aids
- Medical Imaging
- Laser Diode Bonding
- Inkjet and Print Head
- System on a Chip
- System in a Package

